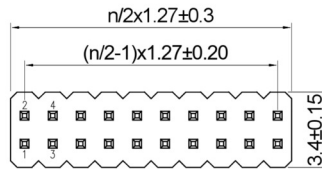
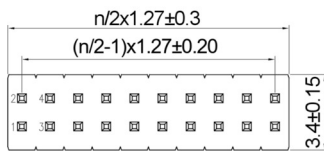


46-751 Economy Version

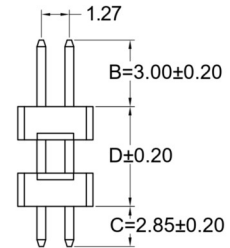
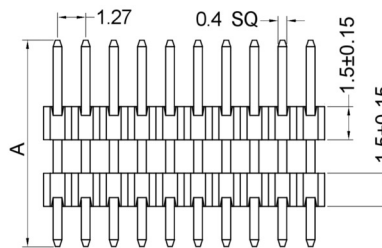
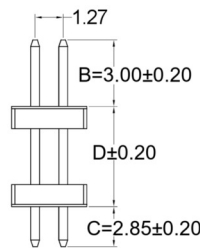
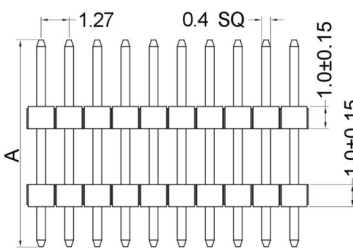
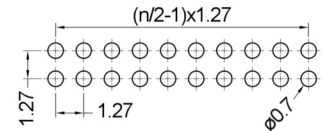
Sandwich-Stiftleisten RM 1,27mm, 2-reihig
Dual Body Pin Headers, 1.27mm Pitch, Double Row

Technische Daten / Technical Data

Isolierkörper	Thermoplast, nach UL94 V-0
<i>Insulator</i>	<i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial	Kupferlegierung
<i>Contact Material</i>	<i>Copper alloy</i>
Kontaktoberfläche	Au über Ni
<i>Contact Surface</i>	<i>Au over Ni</i>
Durchgangswiderstand	< 20 mΩ
<i>Contact Resistance</i>	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
<i>Insulation Resistance</i>	> 1000 MΩ
Spannungsfestigkeit	500 V AC/DC
<i>Test Voltage</i>	<i>500 V AC/DC</i>
Nennstrom	1 A
<i>Current Rating</i>	<i>1 A</i>
Temperaturbereich	-40 °C ... +105 °C
<i>Temperature Range</i>	<i>-40 °C ... +105 °C</i>
Verarbeitung	260 °C für 5 Sekunden
<i>Processing</i>	<i>260 °C for 5 seconds</i>



Recommended P.C.B Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)



Series

46-751

Contacts*

040

004-070 Zweireihig
Double row

Dimensions*

20

20 A=14,30 D=8,45mm
30 A=15,00 D=9,15mm
A/B/C- Kundenspezifisch
A max. 35,0mm; B/C max. 15,0mm
Customer-specific
A max. 35,0mm; B/C max. 15,0mm

Insulator Height*

10

10 H=1,00mm
15 H=1,50mm

Plating

00

00 Vergoldet
Gold plated

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

